

## REMARKS/ARGUMENTS

The Office Action (1) rejected claims 44-47, 51, 52, 78 and 79 under 35 U.S.C 103(a) as being unpatentable over Matsuda et al. (JP 2-301133), in view of LW article (Tailoring Sputtered Cr films on Large Wafer); (2) rejected claims 48-50 and 53-58 under 35 U.S.C 103(a) as being unpatentable over Matsuda et al. and LW article (Tailoring Sputtered Cr films on Large Wafer) as applied to claim 44 above, and further in view of Admitted Prior Art and Stress Control in Multi-Layer Backside Metallization of Thinned Wafers; and (3) allowed claims 1, 3, 4, 22-43, and 59-77.

1, 2. Regarding the rejection based on Matsuda, et al. in view of Lee, et al., Applicant has canceled the claims to overcome the examiner's rejection.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

The Commissioner is authorized to charge any underpayment or credit any overpayment to Deposit Account No. 06-1325 for any matter in connection with this response, including any fee for extension of time, which may be required.

Respectfully submitted,

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